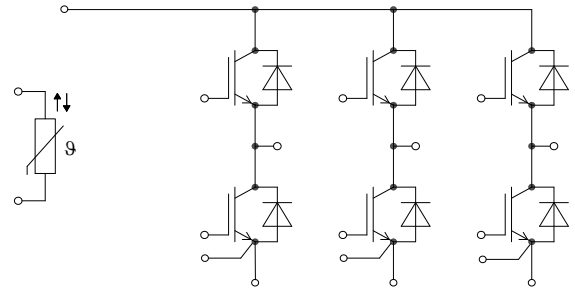
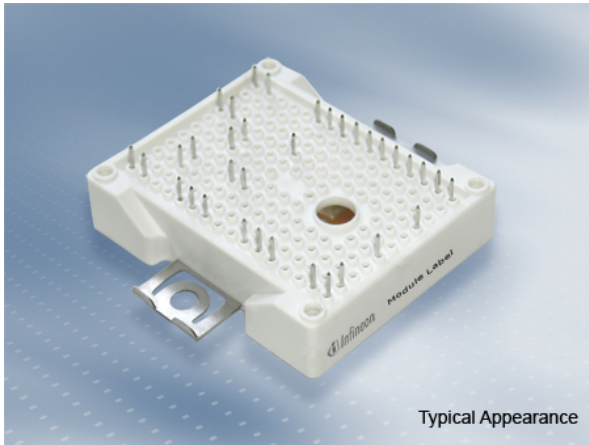


EasyPACK™ Modul mit TRENCHSTOP™ IGBT7 und Emitter Controlled 7 Diode und NTC
 EasyPACK™ module with TRENCHSTOP™ IGBT7 and Emitter Controlled 7 diode and NTC

Vorläufige Daten / Preliminary Data



$V_{CES} = 1200V$
 $I_{C\ nom} = 50A / I_{CRM} = 100A$

Potentielle Anwendungen

- Hilfsumrichter
- Klimaanlage
- Motorantriebe
- Servoumrichter
- USV-Systeme

Potential Applications

- Auxiliary inverters
- Air conditioning
- Motor drives
- Servo drives
- UPS systems

Elektrische Eigenschaften

- Niedriges V_{CEsat}
- Trenchstop™ IGBT7
- Überlastbetrieb bis zu 175°C

Electrical Features

- LOW V_{CEsat}
- Trenchstop™ IGBT7
- Overload operation up to 175°C

Mechanische Eigenschaften

- 2,5 kV AC 1min Isolationsfestigkeit
- Al₂O₃ Substrat mit kleinem thermischen Widerstand
- Hohe Leistungsdichte
- Kompaktes Design
- Lötverbindungstechnik

Mechanical Features

- 2.5 kV AC 1min insulation
- Al₂O₃ substrate with low thermal resistance
- High power density
- Compact design
- Solder contact technology

Module Label Code

Barcode Code 128



DMX - Code



Content of the Code

| Content of the Code | Digit |
|----------------------------|---------|
| Module Serial Number | 1 - 5 |
| Module Material Number | 6 - 11 |
| Production Order Number | 12 - 19 |
| Datecode (Production Year) | 20 - 21 |
| Datecode (Production Week) | 22 - 23 |

IGBT, Wechselrichter / IGBT, Inverter
Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|--|--|-----------|-------|---|
| Kollektor-Emitter-Sperrspannung Collector-emitter voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{CES} | 1200 | V |
| Kollektor-Dauergleichstrom Continuous DC collector current | $T_H = 65^{\circ}\text{C}, T_{vj\max} = 175^{\circ}\text{C}$ | I_{CDC} | 50 | A |
| Periodischer Kollektor-Spitzenstrom Repetitive peak collector current | $t_P = 1\text{ ms}$ | I_{CRM} | 100 | A |
| Gate-Emitter-Spitzenspannung Gate-emitter peak voltage | | V_{GES} | +/-20 | V |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | | |
|--|--|--|---------------------|---------------------------|--------|-------------|---|
| Kollektor-Emitter-Sättigungsspannung Collector-emitter saturation voltage | $I_C = 50\text{ A}$ $V_{GE} = 15\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | $V_{CE\text{ sat}}$ | 1,50 1,64 1,72 | t.b.d. | V V V | |
| Gate-Schwellenspannung Gate threshold voltage | $I_C = 1,28\text{ mA}, V_{CE} = V_{GE}, T_{vj} = 25^{\circ}\text{C}$ | | V_{GEth} | 5,15 | 5,80 | 6,45 | V |
| Gateladung Gate charge | $V_{GE} = -15 / 15\text{ V}, V_{CE} = 600\text{ V}$ | | Q_G | 0,92 | | | μC |
| Interner Gatewiderstand Internal gate resistor | $T_{vj} = 25^{\circ}\text{C}$ | | R_{Gint} | 0,0 | | | Ω |
| Eingangskapazität Input capacitance | $f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{ies} | 11,1 | | | nF |
| Rückwirkungskapazität Reverse transfer capacitance | $f = 100\text{ kHz}, T_{vj} = 25^{\circ}\text{C}, V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}$ | | C_{res} | 0,039 | | | nF |
| Kollektor-Emitter-Reststrom Collector-emitter cut-off current | $V_{CE} = 1200\text{ V}, V_{GE} = 0\text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ | I_{CES} | | | 0,0079 | mA |
| Gate-Emitter-Reststrom Gate-emitter leakage current | $V_{CE} = 0\text{ V}, V_{GE} = 20\text{ V}, T_{vj} = 25^{\circ}\text{C}$ | | I_{GES} | | | 100 | nA |
| Einschaltverzögerungszeit, induktive Last Turn-on delay time, inductive load | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | t_{don} | 0,0183 0,0298 0,035 | | | μs μs μs |
| Anstiegszeit, induktive Last Rise time, inductive load | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Gon} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | t_r | 0,0213 0,024 0,025 | | | μs μs μs |
| Abschaltverzögerungszeit, induktive Last Turn-off delay time, inductive load | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | t_{doff} | 0,27 0,325 0,36 | | | μs μs μs |
| Fallzeit, induktive Last Fall time, inductive load | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}$ $V_{GE} = -15 / 15\text{ V}$ $R_{Goff} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | t_f | 0,12 0,187 0,264 | | | μs μs μs |
| Einschaltverlustenergie pro Puls Turn-on energy loss per pulse | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}, L\sigma = 35\text{ nH}$ $di/dt = 1650\text{ A}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Gon} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | E_{on} | 2,41 4,30 5,45 | | | mJ mJ mJ |
| Abschaltverlustenergie pro Puls Turn-off energy loss per pulse | $I_C = 50\text{ A}, V_{CE} = 600\text{ V}, L\sigma = 35\text{ nH}$ $du/dt = 2900\text{ V}/\mu\text{s} (T_{vj} = 175^{\circ}\text{C})$ $V_{GE} = -15 / 15\text{ V}, R_{Goff} = 5,1\ \Omega$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | E_{off} | 1,90 4,72 6,12 | | | mJ mJ mJ |
| Kurzschlußverhalten SC data | $V_{GE} \leq 15\text{ V}, V_{CC} = 800\text{ V}$ $V_{CEmax} = V_{CES} - L_{SCE} \cdot di/dt$ | $t_P \leq 8\ \mu\text{s}, T_{vj} = 150^{\circ}\text{C}$ $t_P \leq 7\ \mu\text{s}, T_{vj} = 175^{\circ}\text{C}$ | I_{SC} | 190 180 | | | A A |
| Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink | pro IGBT / per IGBT | | R_{thJH} | 0,955 | | | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj\text{ op}}$ | -40 | | 175 | $^{\circ}\text{C}$ |

Diode, Wechselrichter / Diode, Inverter
Höchstzulässige Werte / Maximum Rated Values

| | | | | |
|---|--|-----------|------------|--|
| Periodische Spitzensperrspannung Repetitive peak reverse voltage | $T_{vj} = 25^{\circ}\text{C}$ | V_{RRM} | 1200 | V |
| Dauergleichstrom Continuous DC forward current | | I_F | 50 | A |
| Periodischer Spitzenstrom Repetitive peak forward current | $t_p = 1 \text{ ms}$ | I_{FRM} | 100 | A |
| Grenzlastintegral I^2t - value | $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 125^{\circ}\text{C}$ $V_R = 0 \text{ V}, t_p = 10 \text{ ms}, T_{vj} = 175^{\circ}\text{C}$ | I^2t | 300 250 | A^2s A^2s |

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|--|---|---|-------------|----------------------|--------|---|
| Durchlassspannung Forward voltage | $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ $I_F = 50 \text{ A}, V_{GE} = 0 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | V_F | 1,72 1,59 1,52 | t.b.d. | V V V |
| Rückstromspitze Peak reverse recovery current | $I_F = 50 \text{ A}, -di_F/dt = 1650 \text{ A}/\mu\text{s} (T_{vj}=175^{\circ}\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | I_{RM} | 42,5 53,0 60,5 | | A A A |
| Sperrverzögerungsladung Recovered charge | $I_F = 50 \text{ A}, -di_F/dt = 1650 \text{ A}/\mu\text{s} (T_{vj}=175^{\circ}\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | Q_r | 3,74 8,19 10,4 | | μC μC μC |
| Abschaltenergie pro Puls Reverse recovery energy | $I_F = 50 \text{ A}, -di_F/dt = 1650 \text{ A}/\mu\text{s} (T_{vj}=175^{\circ}\text{C})$ $V_R = 600 \text{ V}$ $V_{GE} = -15 \text{ V}$ | $T_{vj} = 25^{\circ}\text{C}$ $T_{vj} = 125^{\circ}\text{C}$ $T_{vj} = 175^{\circ}\text{C}$ | E_{rec} | 1,72 3,06 3,73 | | mJ mJ mJ |
| Wärmewiderstand, Chip bis Kühlkörper Thermal resistance, junction to heatsink | pro Diode / per diode | | R_{thJH} | 1,22 | | K/W |
| Temperatur im Schaltbetrieb Temperature under switching conditions | | | $T_{vj op}$ | -40 | 175 | $^{\circ}\text{C}$ |

NTC-Widerstand / NTC-Thermistor

Charakteristische Werte / Characteristic Values

| | | | min. | typ. | max. | |
|--|--|--|--------------|------|------|------------|
| Nennwiderstand Rated resistance | $T_{NTC} = 25^{\circ}\text{C}$ | | R_{25} | 5,00 | | k Ω |
| Abweichung von R100 Deviation of R100 | $T_{NTC} = 100^{\circ}\text{C}, R_{100} = 493 \Omega$ | | $\Delta R/R$ | -5 | 5 | % |
| Verlustleistung Power dissipation | $T_{NTC} = 25^{\circ}\text{C}$ | | P_{25} | | 20,0 | mW |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/50}(1/T_2 - 1/(298,15 \text{ K}))]$ | | $B_{25/50}$ | 3375 | | K |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/80}(1/T_2 - 1/(298,15 \text{ K}))]$ | | $B_{25/80}$ | 3411 | | K |
| B-Wert B-value | $R_2 = R_{25} \exp [B_{25/100}(1/T_2 - 1/(298,15 \text{ K}))]$ | | $B_{25/100}$ | 3433 | | K |

Angaben gemäß gültiger Application Note.
Specification according to the valid application note.

Vorläufige Daten Preliminary Data

Modul / Module

| | | | | | | |
|---|---|----------------------|--------------------------------|------|------|----|
| Isolations-Prüfspannung Isolation test voltage | RMS, f = 50 Hz, t = 1 min. | V _{ISOL} | 2,5 | | | kV |
| Innere Isolation Internal isolation | Basisisolation (Schutzklasse 1, EN61140) basic insulation (class 1, IEC 61140) | | Al ₂ O ₃ | | | |
| Kriechstrecke Creepage distance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 11,5 6,3 | | | mm |
| Luftstrecke Clearance | Kontakt - Kühlkörper / terminal to heatsink Kontakt - Kontakt / terminal to terminal | | 10,0 5,0 | | | mm |
| Vergleichszahl der Kriechwegbildung Comperative tracking index | | CTI | > 200 | | | |
| Relativer Temperaturindex (elektr.) RTI Elec. | Gehäuse housing | RTI | 140 | | | °C |
| | | | min. | typ. | max. | |
| Modulstreuinduktivität Stray inductance module | | L _{sCE} | | 40 | | nH |
| Modulleitungswiderstand, Anschlüsse - Chip Module lead resistance, terminals - chip | T _H = 25°C, pro Schalter / per switch | R _{CC'+EE'} | | 4,00 | | mΩ |
| Lagertemperatur Storage temperature | | T _{stg} | -40 | | 125 | °C |
| Anpresskraft für mech. Bef. pro Feder mounting force per clamp | | F | 40 | - | 80 | N |
| Gewicht Weight | | G | | 39 | | g |

Der Strom im Dauerbetrieb ist auf 30 A effektiv pro Anschlusspin begrenzt.

The current under continuous operation is limited to 30 A rms per connector pin.

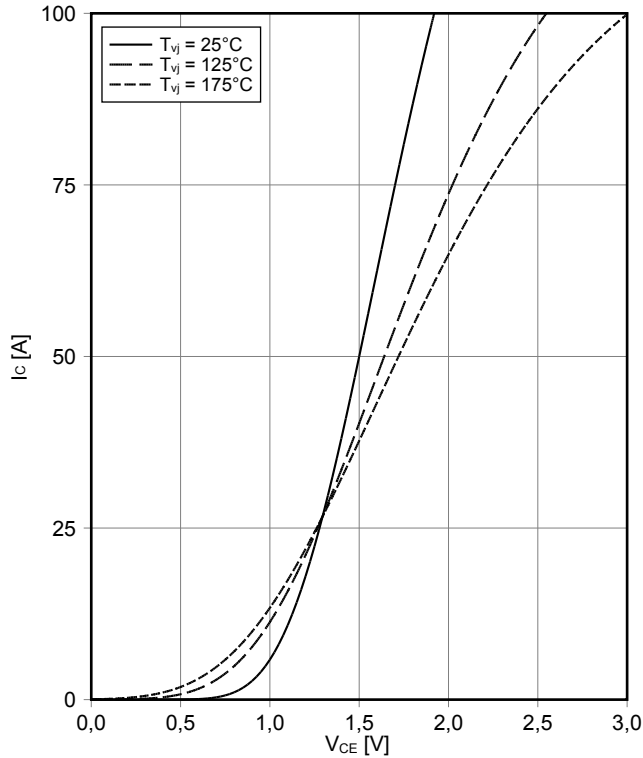
T_{vj op} > 150°C ist im Überlastbetrieb zulässig. Detaillierte Angaben sind AN 2018-14 zu entnehmen.

T_{vj op} > 150°C is allowed for operation at overload conditions. For detailed specifications, please refer to AN 2018-14.

Vorläufige Daten Preliminary Data

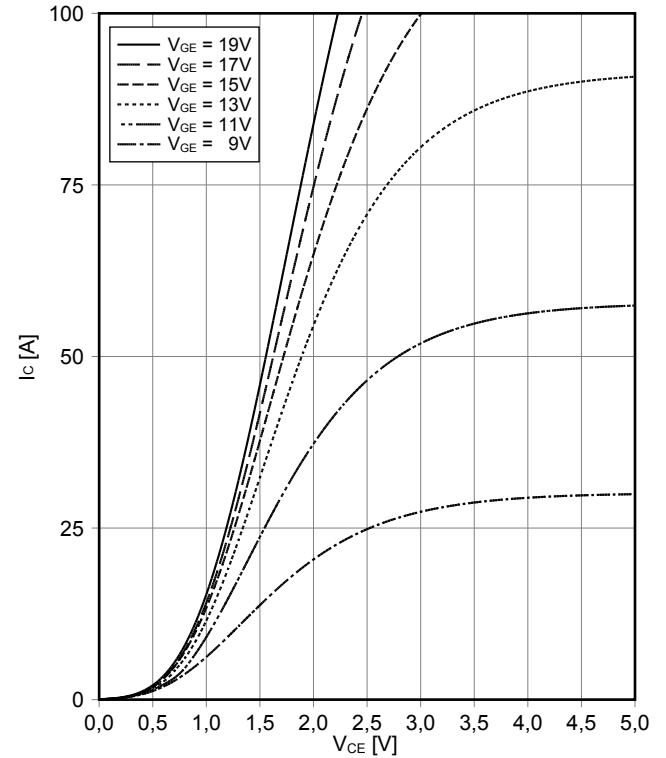
Ausgangskennlinie IGBT, Wechselrichter (typisch) output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $V_{GE} = 15\text{ V}$



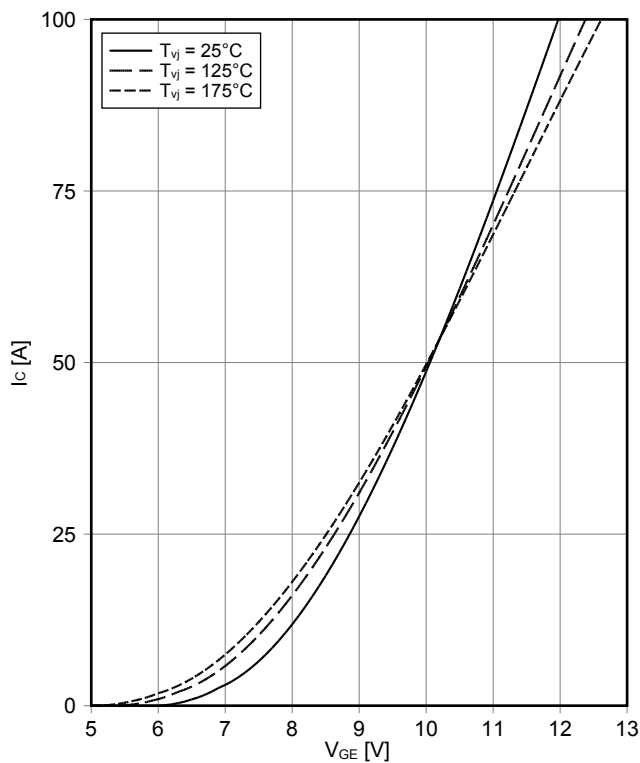
Ausgangskennlinienfeld IGBT, Wechselrichter (typisch) output characteristic IGBT, Inverter (typical)

$I_C = f(V_{CE})$
 $T_{vj} = 175^\circ\text{C}$



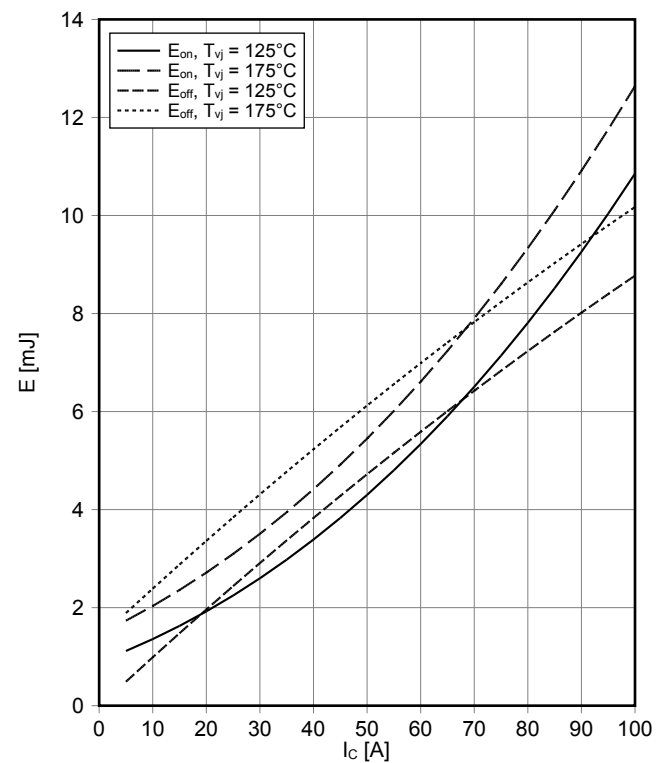
Übertragungscharakteristik IGBT, Wechselrichter (typisch) transfer characteristic IGBT, Inverter (typical)

$I_C = f(V_{GE})$
 $V_{CE} = 20\text{ V}$



Schaltverluste IGBT, Wechselrichter (typisch) switching losses IGBT, Inverter (typical)

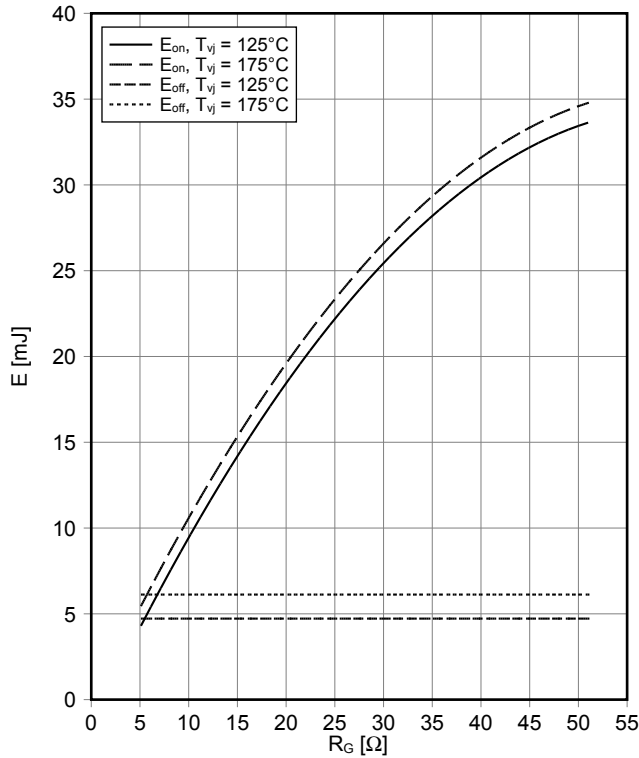
$E_{on} = f(I_C)$, $E_{off} = f(I_C)$
 $V_{GE} = \pm 15\text{ V}$, $R_{Gon} = 5.1\ \Omega$, $R_{Goff} = 5.1\ \Omega$, $V_{CE} = 600\text{ V}$



Vorläufige Daten Preliminary Data

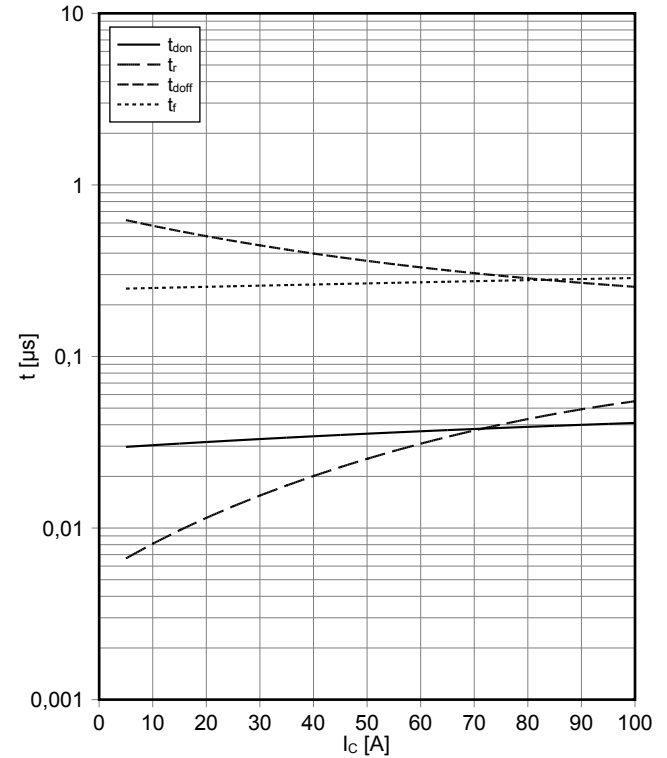
Schaltverluste IGBT, Wechselrichter (typisch) switching losses IGBT, Inverter (typical)

$E_{on} = f(R_G), E_{off} = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 50\text{ A}, V_{CE} = 600\text{ V}$



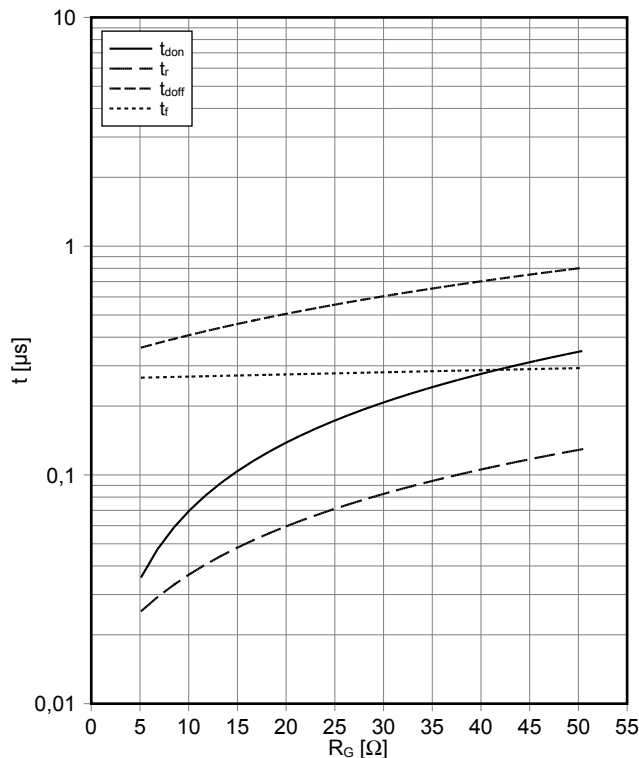
Schaltzeiten IGBT, Wechselrichter (typisch) switching times IGBT, Inverter (typical)

$t_{don} = f(I_C), t_r = f(I_C), t_{doff} = f(I_C), t_f = f(I_C)$
 $V_{GE} = \pm 15\text{ V}, R_{Gon} = 5.1\ \Omega, R_{Goff} = 5.1\ \Omega, V_{CE} = 600\text{ V}, T_{vj} = 175^\circ\text{C}$



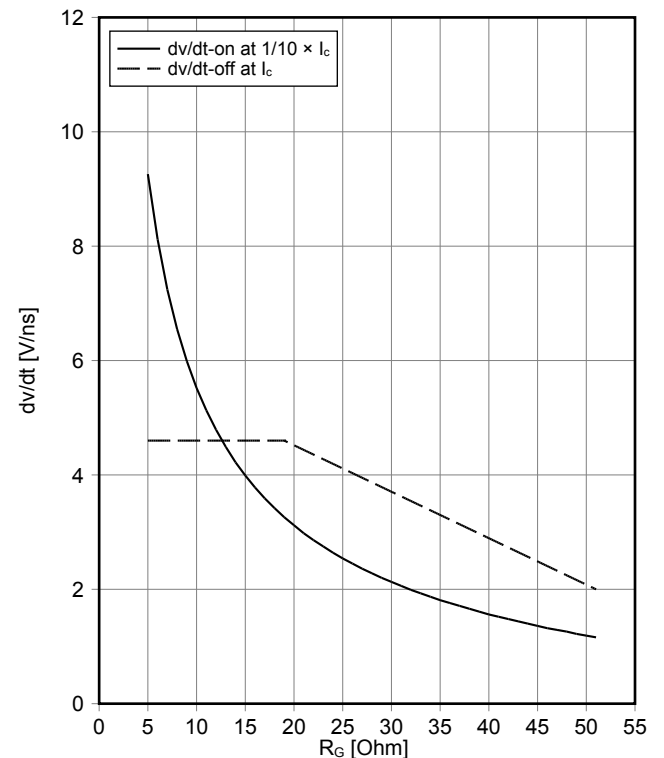
Schaltzeiten IGBT, Wechselrichter (typisch) switching times IGBT, Inverter (typical)

$t_{don} = f(R_G), t_r = f(R_G), t_{doff} = f(R_G), t_f = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 50\text{ A}, V_{CE} = 600\text{ V}, T_{vj} = 175^\circ\text{C}$



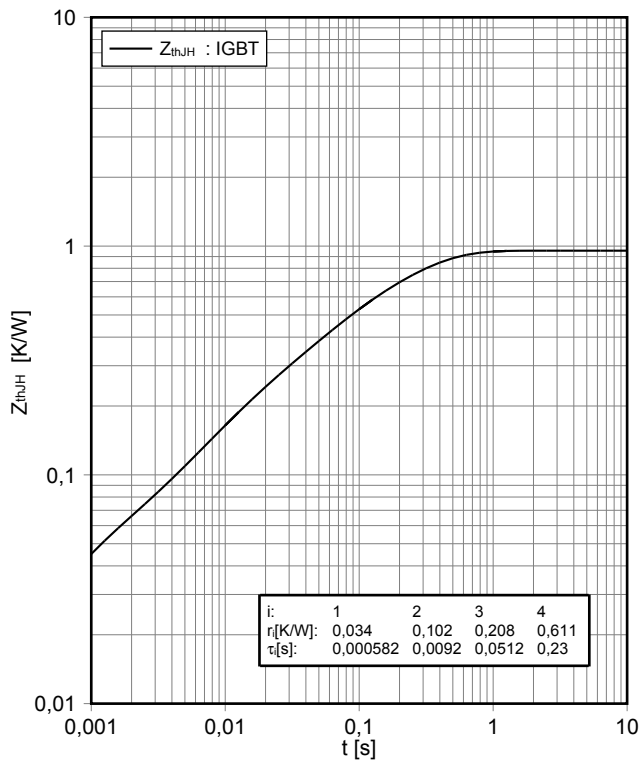
dv/dt IGBT, Wechselrichter (typisch) dv/dt IGBT, Inverter (typical)

$dv/dt = f(R_G)$
 $V_{GE} = \pm 15\text{ V}, I_C = 50\text{ A}, V_{CE} = 600\text{ V}, T_{vj} = 25^\circ\text{C}$

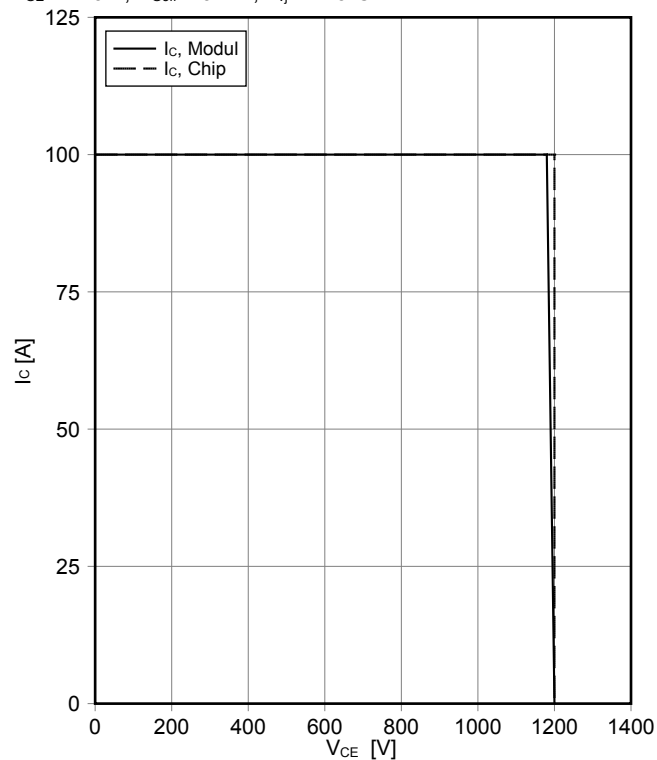


Vorläufige Daten Preliminary Data

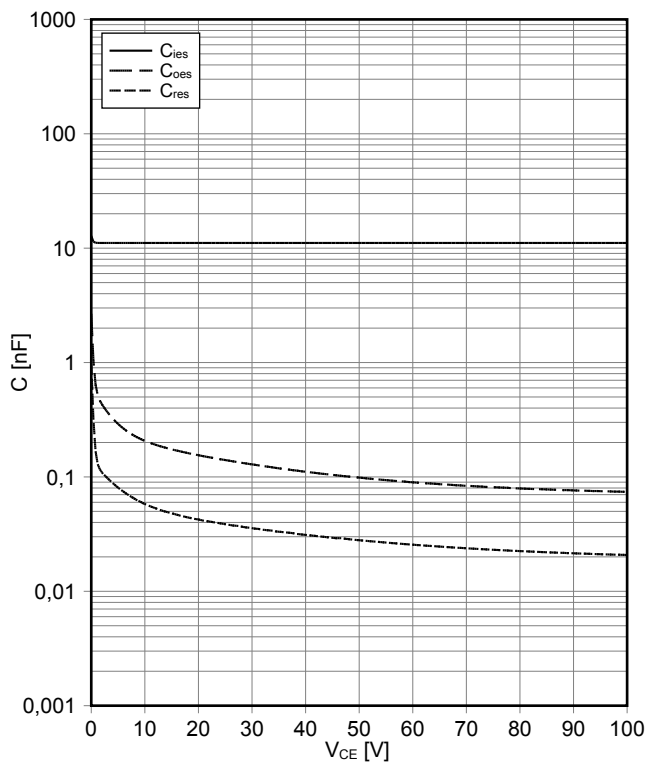
Transienter Wärmewiderstand IGBT, Wechselrichter
transient thermal impedance IGBT, Inverter
 $Z_{thJH} = f(t)$



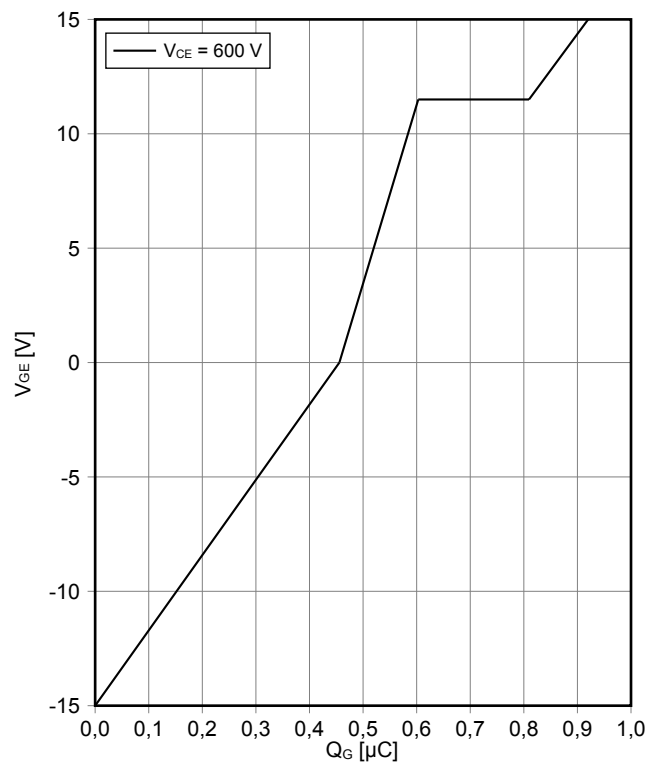
Sicherer Rückwärts-Arbeitsbereich IGBT, Wechselrichter (RBSOA)
reverse bias safe operating area IGBT, Inverter (RBSOA)
 $I_C = f(V_{CE})$
 $V_{GE} = \pm 15 \text{ V}$, $R_{Goff} = 5.1 \Omega$, $T_{vj} = 175^\circ\text{C}$



Kapazitäts Charakteristik IGBT, Wechselrichter (typisch)
capacity characteristic IGBT, Inverter (typical)
 $C = f(V_{CE})$
 $V_{GE} = 0 \text{ V}$, $T_{vj} = 25^\circ\text{C}$, $f = 100\text{kHz}$

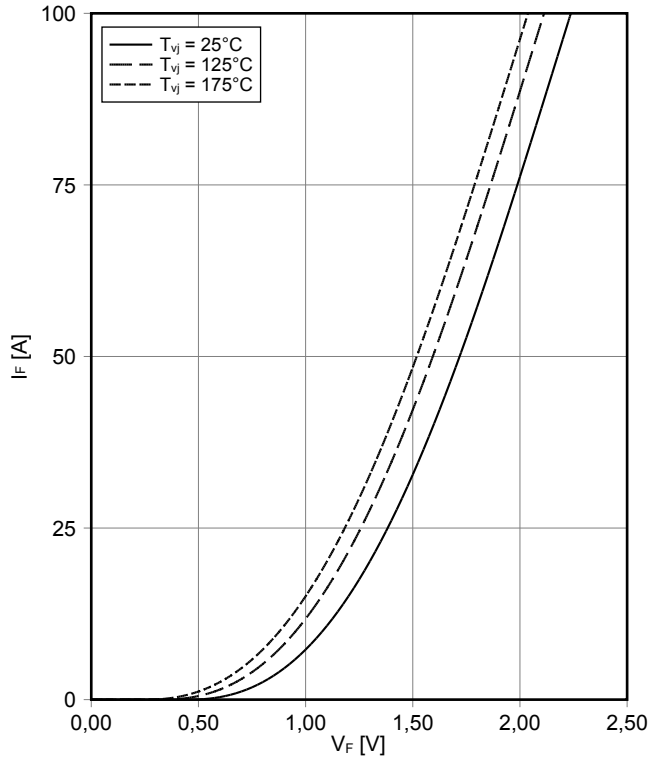


Gateladungs Charakteristik IGBT, Wechselrichter (typisch)
gate charge characteristic IGBT, Inverter (typical)
 $V_{GE} = f(Q_G)$
 $I_C = 50 \text{ A}$, $T_{vj} = 25^\circ\text{C}$

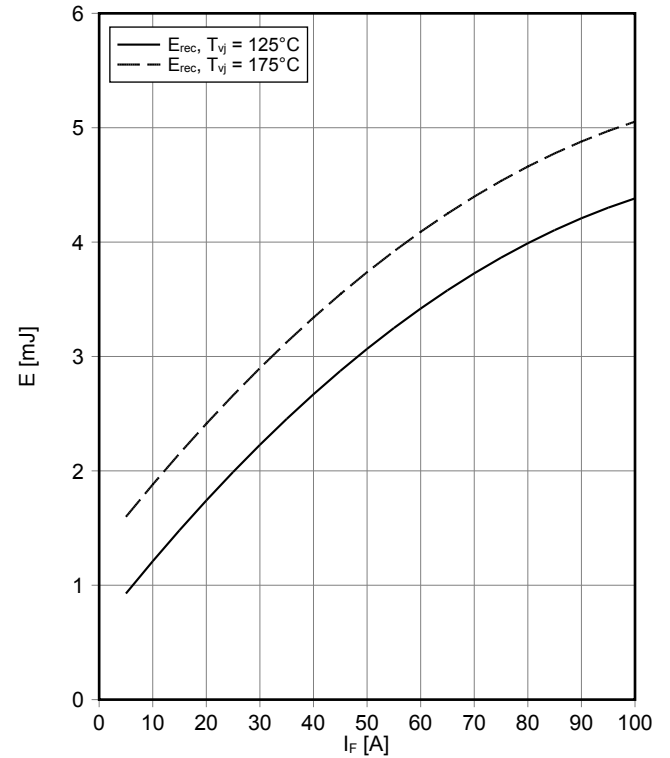


Vorläufige Daten Preliminary Data

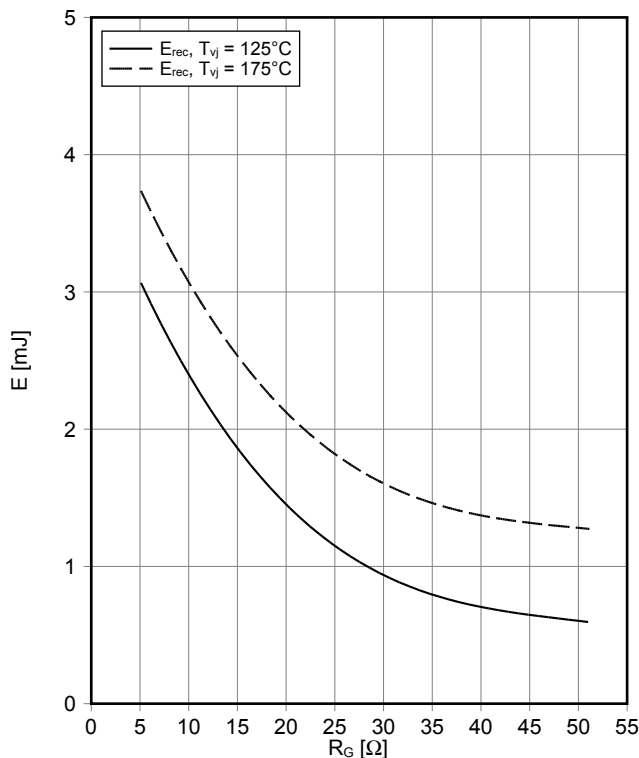
Durchlasskennlinie der Diode, Wechselrichter (typisch)
forward characteristic of Diode, Inverter (typical)
 $I_F = f(V_F)$



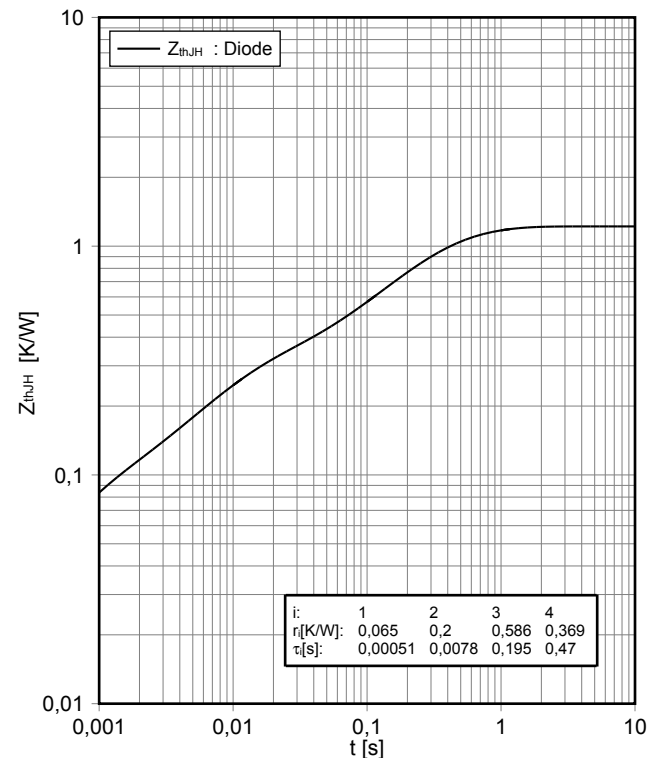
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)
 $E_{rec} = f(I_F)$
 $R_{Gon} = 5.1 \Omega, V_{CE} = 600 \text{ V}$



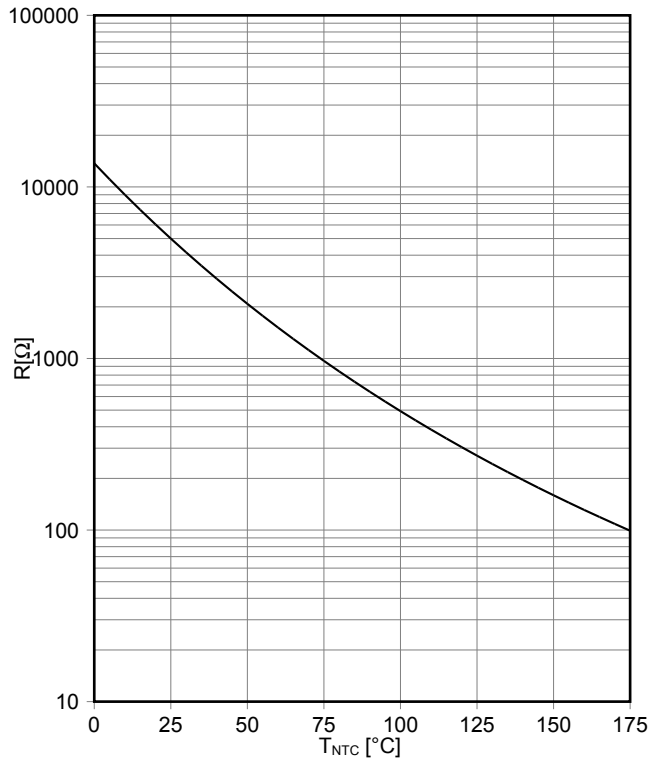
Schaltverluste Diode, Wechselrichter (typisch)
switching losses Diode, Inverter (typical)
 $E_{rec} = f(R_G)$
 $I_F = 50 \text{ A}, V_{CE} = 600 \text{ V}$



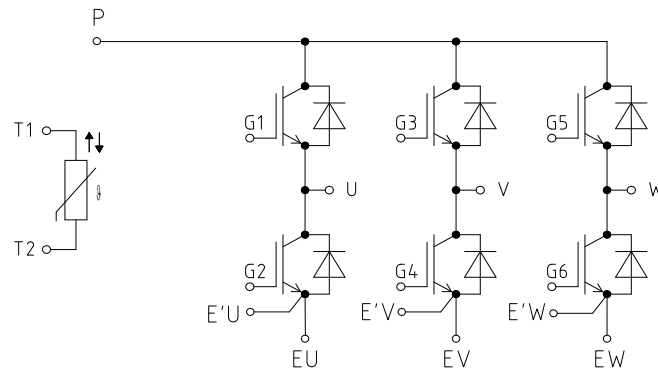
Transienter Wärmewiderstand Diode, Wechselrichter
transient thermal impedance Diode, Inverter
 $Z_{thJH} = f(t)$



NTC-Widerstand-Temperaturkennlinie (typisch)
NTC-Thermistor-temperature characteristic (typical)
 $R = f(T_{NTC})$



Schaltplan / Circuit diagram



Gehäuseabmessungen / Package outlines

